MOVABLE BODY APPARATUS, EXPOSURE APPARATUS AND EXPOSURE METHOD, FINE MOVEMENT MEMBER, AND DEVICE MANUFACTURING METHOD

ABSTRACT

Power-transmitting, waste-heat frames (24A, 24B) can continually absorbs heat radiated from wafer stages (WST1, WST2), and therefore it becomes possible to suppress adverse influence on exposure accuracy due to the heat generated at the wafer stages (WST1, WST2). In this case, unlike the conventional method, it is not necessary to connect a conduit (tube) for supplying coolant to the wafer stages (WST1, WST2) from the outside, and accordingly declines in movement accuracy of the wafer stages (WST1, WST2) due to tension of such a conduit can be prevented. Also from this standpoint, the exposure accuracy can be maintained at high accuracy.